



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

| | | | |
|------------|--|---------------------------|--|
| 1752-2 1.1 | IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x | Form Type * Distribute | Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat |
|------------|--|---------------------------|--|

Supplier Information

| | | | | | | | | |
|---|---|--------------------------------|--------------------------------|--|-----------------------------------|----------|-----|-----------|
| Company Name * STMicroelectronics | Company Unique ID | Unique ID Authority | Response Date * NA | Response Document ID | | | | |
| Contact Name * | Title - Contact | Phone - Contact * | Email - Contact * | <input type="button" value="Duplicate Contact -> Authorized Representative"/> | | | | |
| Authorized Representative * GIOVANNI GIACOPELLO | Title - Representative APM MD CHAMPION | Phone - Representative * NA | Email - Representative * NA | Supplier Comments or URL for Additional Information | | | | |
| Requester Item Number | Mfr Item Number | Mfr Item Name | Effective Date | Version | Manufacturing Site | Weight * | UOM | Unit Type |
| | STPS20L45CT | HSDZ*F55Q02Y | 2010-12-14 | A | SH1A | 1,900 | mg | Each |
| Alternate Recommendation | TO 220 AB NON ISOL | | | Alternate Item Comments | ECOPACK2/ROHS BSA REF: CD00243715 | | | |

Manufacturing Process Information

| | | | | | |
|---|--|---|------------------------------------|---|-------------------------|
| Terminal Plating / Grid Array Material Matte Tin (Sn) | Terminal Base Alloy CU Alloy | J-STD-020 MSL Rating Not Applicable | Peak Process Body Temperature C | Max Time at Peak Temperature seconds | Number of Reflow Cycles |
|---|--|---|------------------------------------|---|-------------------------|

Comments
DISCLAIMER: While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict "as is"

Save the fields in this form to a file

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Import Data

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Lock the fields on this form to prevent changes

Lock Supplier Fields

RoHS Material Composition Declaration

Declaration Type *

Simplified

RoHS Directive
2002/95/EC

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration *

3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any

Supplier Acceptance *

Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version

EL-2006/690/EC

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7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

| | Item/SubItem Name | | Homogeneous Material | Weight | Unit of Measure | | Level | Substance Category | | Substance | CAS | Exempt | Weight | Unit of Measure | Tolerance | | PPM | |
|----|-------------------|--------------|----------------------|-------------------|-----------------|----|-------|--------------------|--------------------|-----------|----------------------|-------------|----------|-----------------|-----------|---|-----|---------|
| | | | | | | | | | | | | | | | - | + | | |
| +I | -I | HSDZ*F55Q02Y | +M -M | Silicon Die | 7.019 | mg | +C -C | Supplier | Silicon die | +S -S | Silicon | 7440-21-3 | | 6.775 | mg | | | 965,23 |
| | | | | | | | | | Die metallization | +S -S | Aluminium(Al) | 7429-90-5 | | 0.211 | mg | | | 30,061 |
| | | | | | | | | | | +S -S | Nickel (Ni) | 7440-02-0 | | 0.003 | mg | | | 427 |
| | | | | | | | | | | +S -S | Titanium (Ti) | 7440-32-6 | | 0.03 | mg | | | 4,274 |
| | | | +M -M | Leadframe | 1,247.19 | mg | +C -C | Supplier | Alloy | +S -S | Copper (Cu) | 7440-50-8 | | 1,245.569 | mg | | | 998,70 |
| | | | | | | | | | | +S -S | Iron (Fe) | 7439-89-6 | | 1.247 | mg | | | 1,000 |
| | | | | | | | | | | +S -S | Iron Phosphide (FeP) | 26508-33-8 | | 0.374 | mg | | | 300 |
| | | | +M -M | Leadframe coating | 4.26 | mg | +C -C | Supplier | Coating | +S -S | Nickel (Ni) | 7440-02-0 | | 3.977 | mg | | | 933,56 |
| | | | | | | | | | | +S -S | Phosphorus (P) | 12185-10-3 | | 0.283 | mg | | | 66,432 |
| | | | +M -M | Die Attach | 2.789 | mg | +C -C | A | Lead/Lead Compound | +S -S | Lead (Pb) | 7439-92-1 | 7a. Lead | 2.663 | mg | | | 954,82 |
| | | | | | | | | | Soft solder | +S -S | Silver (Ag) | 7440-22-4 | | 0.07 | mg | | | 25,099 |
| | | | | | | | | | | +S -S | Tin (Sn) | 7440-31-5 | | 0.056 | mg | | | 20,079 |
| | | | +M -M | Bonding wire | 5.144 | mg | +C -C | Supplier | Bonding wire | +S -S | Aluminium (Al) | 7429-90-5 | | 5.144 | mg | | | 1,000,0 |
| | | | +M -M | Encapsulation | 624.51 | mg | +C -C | Supplier | Moulding Compound | +S -S | Epoxy resin | 60676-86-0 | | 124.902 | mg | | | 200,00 |
| | | | | | | | | | | +S -S | Silica, vitreous | 60676-86-0 | | 397.812 | mg | | | 636,99 |
| | | | | | | | | | | +S -S | phenolic resin | 9003-35-4 | | 62.451 | mg | | | 100,00 |
| | | | | | | | | | | +S -S | metal hydroxide | Proprietary | | 37.471 | mg | | | 60,001 |
| | | | | | | | | | | +S -S | carbon black | 1333-86-4 | | 1.874 | mg | | | 3,000 |
| | | | +M -M | Finishing | 9.088 | mg | +C -C | Supplier | Connection coating | +S -S | Tin (Sn) | 7440-31-5 | | 9.088 | mg | | | 1,000,0 |